DIN Rail Snap-In-Jack Module

Datasheet: GD065827v6



APPLICATION

The Brand-Rex DIN Rail SIJ Module offers a connection point in the cabling subsystem and is suitable for deployment in residential, industrial and enterprise structured cabling systems. The module is designed to be easily snapped onto a DIN rail and it offers unrivalled usability and accessibility. Multiple modules can be aligned horizontally in a row and the angled direction of the jacks facilitates cord routing in a way that eases bending stresses while maximising performance.

FEATURES

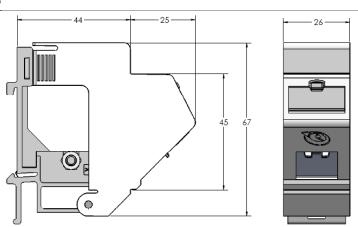
- Suitable for Brand-Rex approved Snap-in-Jacks both screened and unscreened
- Attaches to Din Rail 35mm x 7.5mm EN60715
- IP Rate 20
- DIN rail earth / grounding clip
- Colour light grey RAL 7035
- Port protected with shutter door
- Label identification
- Detachable cover



ORDER INFO

Brand-Rex Part Number	Item Description	Colour	Weight per Item (nom)	Qty per Pack
MMCDINSIJS8	DIN Rail SIJ Module	Grey	30g	4

PHYSICAL CHARACTERISTICS



MATERIALS

PC 10% GF

- Stainless Steel Grounding Clip
- Packaging fully recyclable card

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ENVIRONMENTAL CONDITIONS

• Storage temperature from -40°C to 70°C

 Operating temperature from -10°C to 60°C at 93% relative humidity, non-condensing

COMPATIBILITY MATRIX

Catalogue Number	Description
AC6JAKS000DC	10GPlus Cat 6A Shielded Tool-free Snap-In Jack
C6CJAKS000DC	Cat6Plus Cat 6 Shielded Tool-free Snap-In Jack
AC6JAKU002	10GPlus Cat 6A Unshielded Tool-free Snap-In Jack
C6CJAKU002	Cat6Plus Cat 6 Unshielded Tool-free Snap-In Jack
GPCJAKU002	GigaPlus Cat 5e Unshielded Tool-free Snap-In Jack

"Brand-Rex is **dedicated** to **designing**, **developing** and **manufacturing** sustainable **high performance** structured cabling and speciality **cabling solutions**"

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